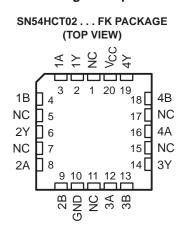
SCLS065E - NOVEMBER 1988 - REVISED JULY 2003

- Operating Voltage Range of 4.5 V to 5.5 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-μA Max I_{CC}

SN54HCT02 ... J OR W PACKAGE SN74HCT02 ... D, DB, N, NS, OR PW PACKAGE (TOP VIEW)

- Typical t_{pd} = 10 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible



NC - No internal connection

description/ordering information

These devices contain four independent 2-input NOR gates. They perform the Boolean function $Y = \overline{A} \bullet \overline{B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ТА	PACKA	GEŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HCT02N	SN74HCT02N
		Tube of 50	SN74HCT02D	
	SOIC – D	Reel of 2500	SN74HCT02DR	HCT02
–40°C to 85°C		Reel of 250	SN74HCT02DT	
	SOP – NS	Reel of 2000	SN74HCT02NSR	HCT02
	SSOP – DB	Reel of 2000	SN74HCT02DBR	HT02
		Tube of 90	SN74HCT02PW	
	TSSOP – PW	Reel of 2000	SN74HCT02PWR	HT02
		Reel of 250	SN74HCT02PWT	
	CDIP – J	Tube of 25	SNJ54HCT02J	SNJ54HCT02J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HCT02W	SNJ54HCT02W
	LCCC – FK Tube of 55		SNJ54HCT02FK	SNJ54HCT02FK

ORDERING INFORMATION

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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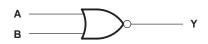


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FUNCTION TABLE (each gate)							
INP	UTS	OUTPUT					
Α	В	Y					
Н	Х	L					
Х	Н	L					
L	L	н					

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see N Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see N Continuous output current, I_O ($V_O = 0$ to V_{CC}) Continuous current through V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 2): D	-0.5 V to 7 V Note 1)
	<i>N</i> package 113°C/W –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN	154HCT02	SN	74HCT0	2	UNIT
			MIN	NOM MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5 🔥 5.5	4.5	5	5.5	V
VIH	High-level input voltage	V _{CC} = 4.5 V to 5.5 V	2	N	2			V
VIL	Low-level input voltage	V_{CC} = 4.5 V to 5.5 V		0.8			0.8	V
VI	Input voltage		0	Vcc	0		VCC	V
VO	Output voltage		0	S Vcc	0		VCC	V
$\Delta t/\Delta v$	Input transition rise/fall time		C	500			500	ns
Τ _Α	Operating free-air temperature		-55	125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics	over	recommended	operating	free-air	temperature	range	(unless
otherwise noted)					-	•	

PARAMETER	TEST CONDITIONS		Vaa	T _A = 25°C			SN54HCT02		SN74HCT02		UNIT
PARAMETER	TEST CO	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
Veu	$V_{I} = V_{IH} \text{ or } V_{IL}$	I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		V
VOH	VI = VIH OL VIL	I _{OH} = -4 mA	4.5 V	3.98	4.3		3.7	<u>h</u>	3.84		v
Ve	$V_{I} = V_{IH} \text{ or } V_{IL} \qquad \frac{I_{OL} = 20 \ \mu\text{A}}{I_{OL} = 4 \ \text{mA}}$	I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	V
VOL		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	v
li	AI = ACC or 0		5.5 V		±0.1	±100	1	±1000		±1000	nA
ICC	$V_I = V_{CC} \text{ or } 0,$	$I_{O} = 0$	5.5 V			2	202	40		20	μA
∆lcc‡	One input at 0.5 V of Other inputs at 0 or	,	5.5 V		1.4	2.4	PPO4	3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10		10	pF

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

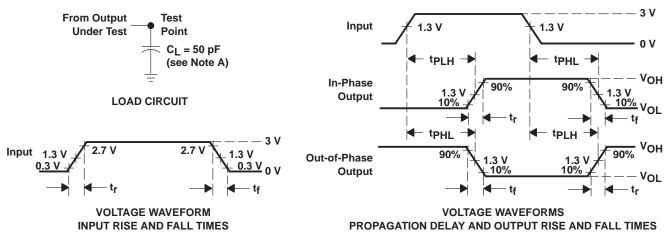
PARAMETER	FROM TO		FROM TO		PAMETED FROM TO		Vaa	Т	ן = 25°C	;	SN54HCT02	SN74HCT02	UNIT
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN MAX	MIN MAX	UNIT				
÷.	A or B	V	4.5 V		11	20	30	25	20				
чрd	^t pd A or B	T	5.5 V		10	18	27	22	ns				
		V	4.5 V		9	15	22	19					
t _t		ř	5.5 V		8	14	20	17	ns				

operating characteristics, T_{A} = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	No load	20	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_Q = 50 Ω, t_r = 6 ns, t_f = 6 ns.
 - C. The outputs are measured one at a time with one input transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms



24-Jun-2005

PACKAGING INFORMATION

MENTS

www ti com

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74HCT02D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HCT02DE4	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HCT02DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HCT02DRE4	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HCT02DT	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HCT02DTE4	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HCT02N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HCT02NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HCT02NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HCT02NSRE4	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HCT02PW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HCT02PWE4	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HCT02PWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HCT02PWRE4	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HCT02PWT	ACTIVE	TSSOP	PW	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HCT02PWTE4	ACTIVE	TSSOP	PW	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined. **Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that an

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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